Innovative DC/DC Power Modules

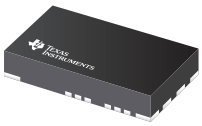
TEXAS INSTRUMENTS

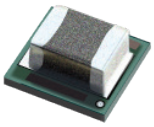
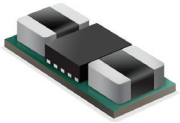
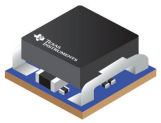
Overview

TI's broad range of DC/DC power modules are designed specifically to help designers get to market faster with validated, high performance solutions. In a single package, these power modules integrate inductors, FETs, compensation, and other passive components to reduce development time for design and verification, and speed up time to market with proven reliability.

To browse the entire portfolio and learn more on the latest products, visit: **ti.com/powermodules**

Featured Products

TPSM846C23 	• 4.5V to 15V_{IN} • 35A Output; Parallel for 70A • PMBus v1.3 Command Set • 15 x 16 x 6.5mm • TPSM846C24 for Non-PMBus
TPSM84203/05/12 	• 4.5 to 28V_{IN} • Fixed 3.3V, 5V and 12V Outputs • 1.5A Output Current • Low EMI with Spread Spectrum • Pin-Pin Wth TO-220 Package
LMZM33602/03 	• 4.0 to 36V_{IN} • 2.4 to 18V_{OUT} • 2A/3A Output Current • 7 x 9 x 3.8mm Package • Forced PWM and Low EMI
TPSM84A21/2 	• 8V to 14V_{IN} • 10A Output Current • 0.55 to 2.05V_{OUT} • Only One External Component • 15 x 9 x 2.3mm Package

TPS82130/40/50 	• 3V to 17V_{IN} • 1, 2 and 3A Output Current Options • 0.9 to 5V_{OUT} • Tiny 2.8 x 3.0 x 1.5mm Package • Light Load Efficient
TPSM82480 	• 2.4 to 5.5V_{IN} • Tiny 3.6 x 7.9 x 1.5mm Package • 0.6 to 5.0V_{OUT} at 6A • Light Load Efficiency or Fixed Freq.
LMZM23600/1 	• 4V to 36V_{IN} • 1A and 0.5A Output Current Options • Fixed 5V, 3.3V and Adj V_{OUT} to 15V • Tiny 3.8 x 3.0 x 1.6mm Package
TPSM84824/624/424 	• 4.5 to 17V_{IN} • 8A, 6A and 4A Output Current • 0.6V to 10V_{OUT} • 7.5 x 7.5 x 5.3mm Package • TurboTrans™ Fast Transient Response

Why Power Modules?

Smaller Size

LM46002



288mm^2

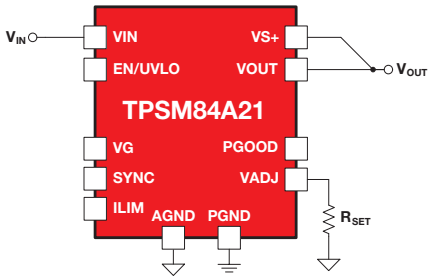
LMZ36002



196mm^2

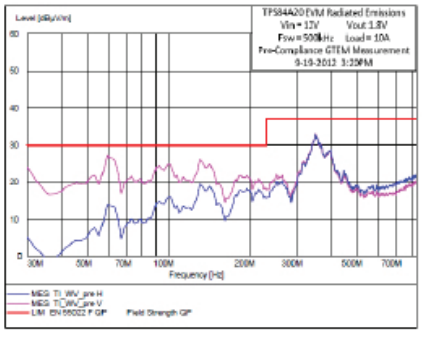
- Module smaller vs discrete

Simple Solutions



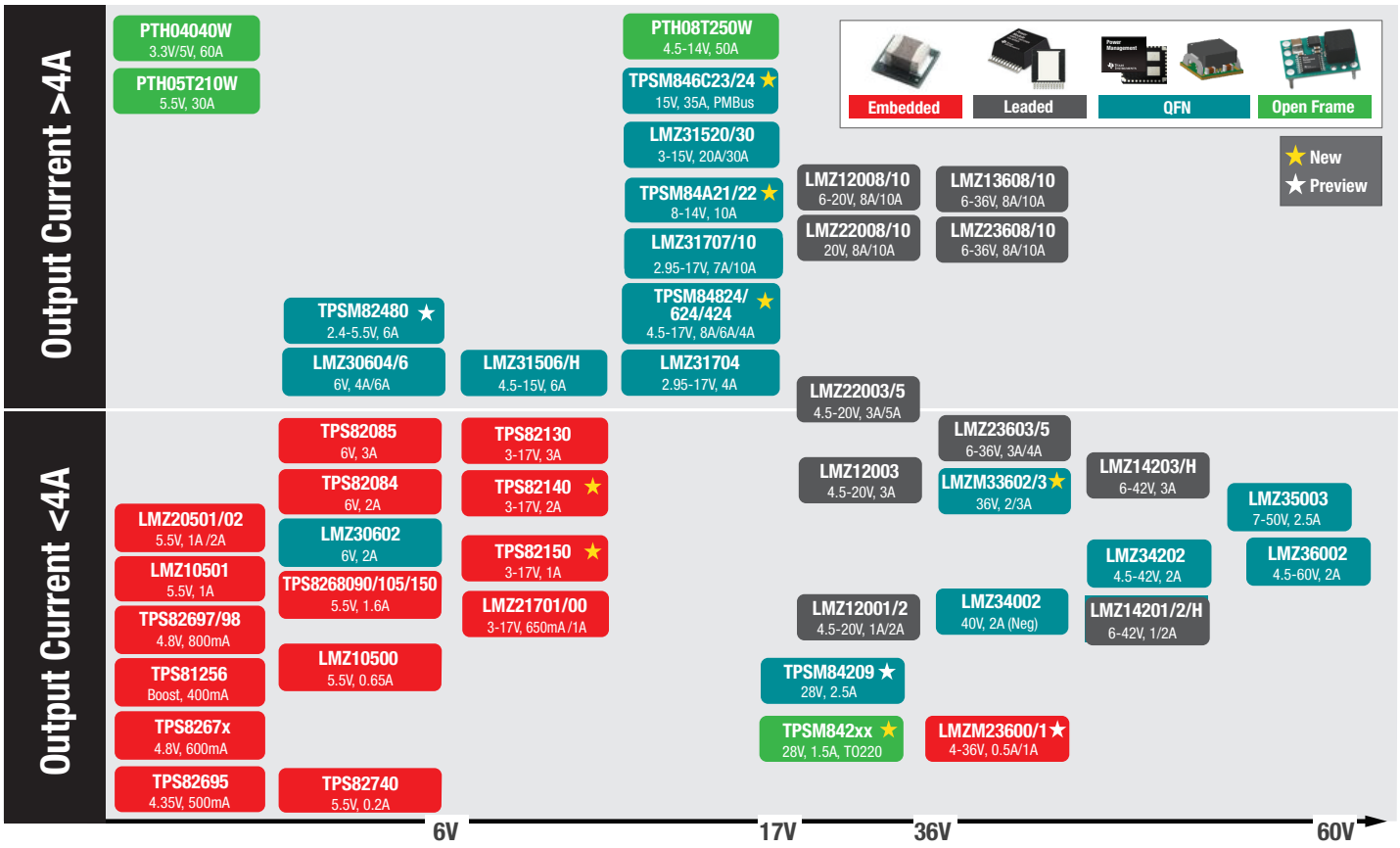
- Minimal components

Low EMI

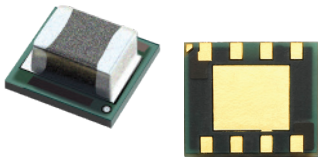
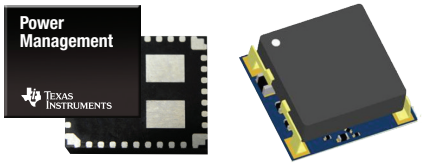
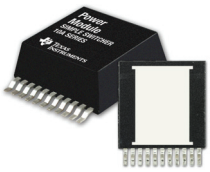


- Tested EMI performance

TI's Power Module Portfolio



TI Module Packages (Select)

	Embedded	QFN	Leaded
Package Outline	**BGA / LGA (QFN-like)** 	**QFN Style** 	**TO-Style** 
Description	LGA QFN Pinless Package Embedded Die in FR Laminate (LGA or BGA Pads). MSL2/3 Highest Density Package	QFN-Style Pinless Package Single Copper Leadframe MSL3 Size Optimized Package Excellent Thermals	TO-Style Pinned Package Dual Copper Leadframe 7 and 11 Pin Versions. MSL3 Large Single Thermal Pad Easy to Use

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